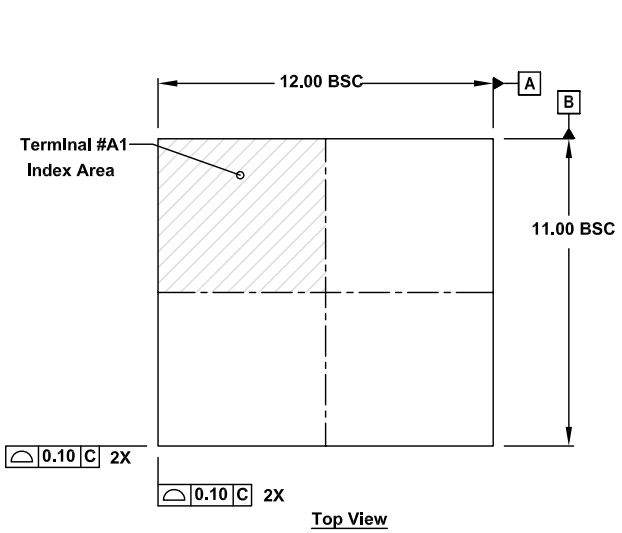
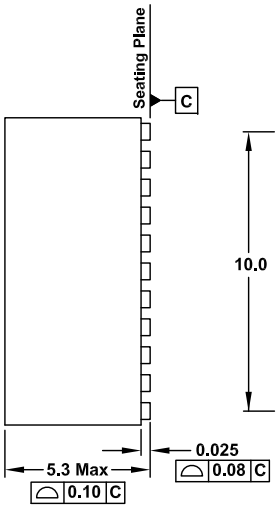
Package Outline Drawing

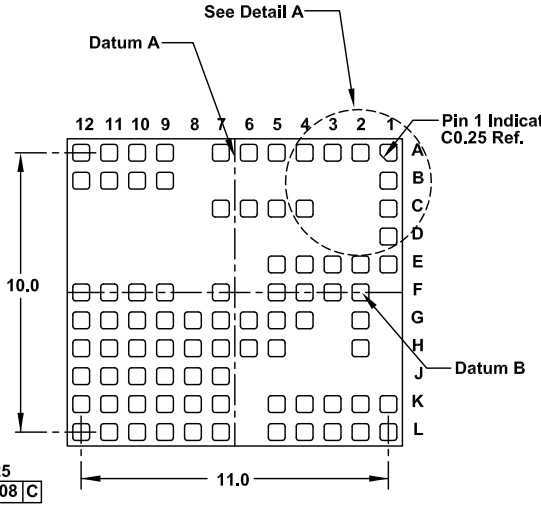
Y83.12x11
83 I/O 12mmx11mmx5.3mm HDA Module
Rev 0, 3/18



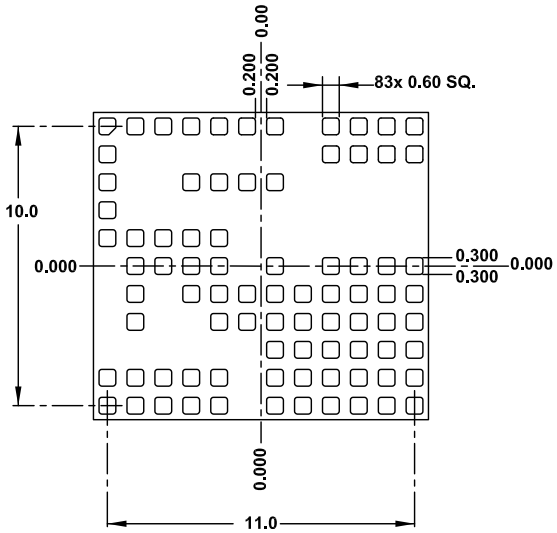
Top View



Side View

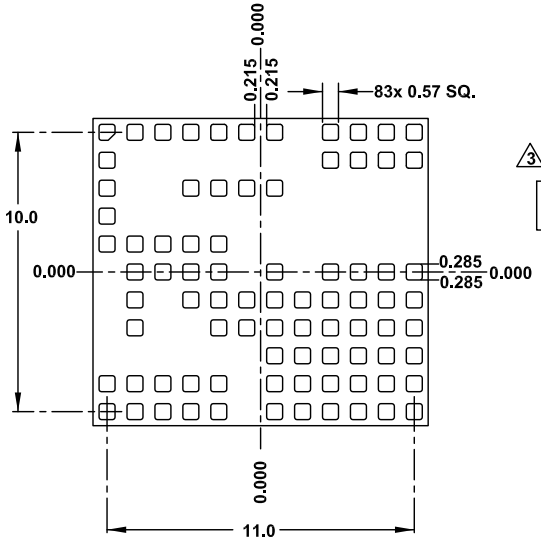


Bottom View



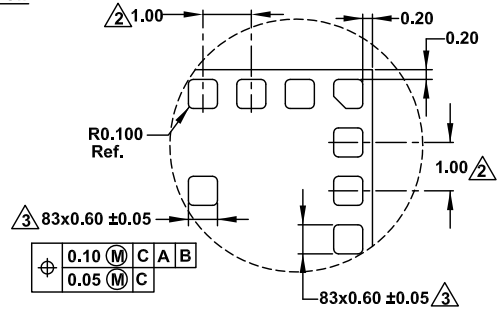
Recommended Positive Solder Mask Defined PCB Land Pattern

Top View



Recommended Solder Stencil

Top View



Detail A

NOTES:

1. All dimensions are in millimeters.
2. Represents basic land grid pitch.
3. These 83 I/O are centered in a fixed row. and column matrix at 1.0mm pitch BSC.
4. Dimensioning and tolerancing per ASME Y14.5-2009.